

## **In the Claims**

Claim 1 (canceled).

Claim 2 (currently amended): The semiconductor package of claim 4 7 wherein the dielectric support member is a photomask material.

Claim 3 (currently amended): The semiconductor package of claim 4 7 wherein the dielectric support member is not a photomask material.

Claim 4 (currently amended): The semiconductor package of claim 4 7 wherein the one or more circuit traces comprise copper.

Claims 5 and 6 (canceled).

Claim 7 (currently amended): ~~The semiconductor package of claim 1~~ A  
semiconductor package, comprising:

an interposer construction containing only a single dielectric support member and  
comprising a plurality of conductive circuit traces contacting the single dielectric support  
member;

a semiconductor die electrically connected with at least one of the traces;

at least one of the circuit traces being between the semiconductor die and the  
dielectric support member;

~~wherein the dielectric support member is patterned to have~~ having a first surface  
and an opposing second surface, the circuit traces being over the first surface, openings  
extending therein, the package further comprising: through the second surface to at least  
some of the circuit traces;

contact pads within one or more of the openings and in electrical connection with the  
one or more of the circuit traces, the contact pads being entirely contained within the  
openings; and

solder balls in electrical connection with the contact pads.

Claim 8 (currently amended): The semiconductor package of claim 4 7 wherein:  
the dielectric support member has a slit extending therethrough; and  
~~the dielectric support member has one or more openings extending therethrough for~~  
~~electrical connection to the one or more circuit traces; and~~  
the electrical connection of the semiconductor die to said at least one of the circuit  
traces includes one or more wire bonds extending from the die, through the slit, and into at  
least one of the openings.

Claims 9-56 (canceled).